

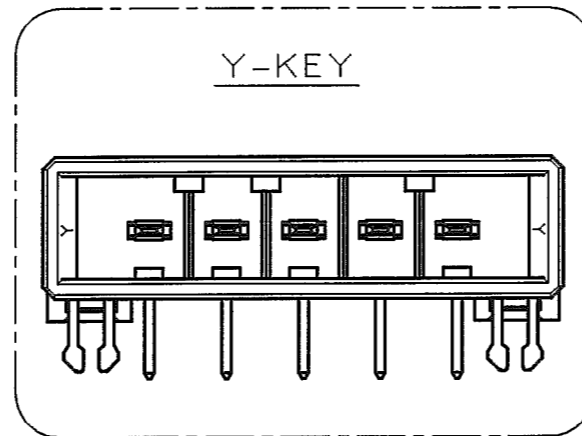
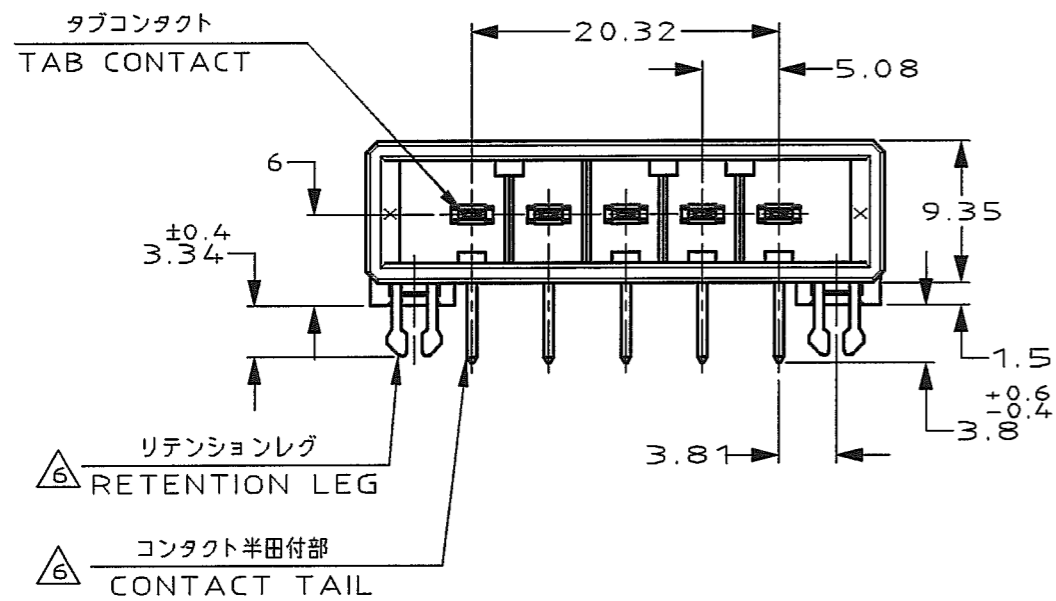
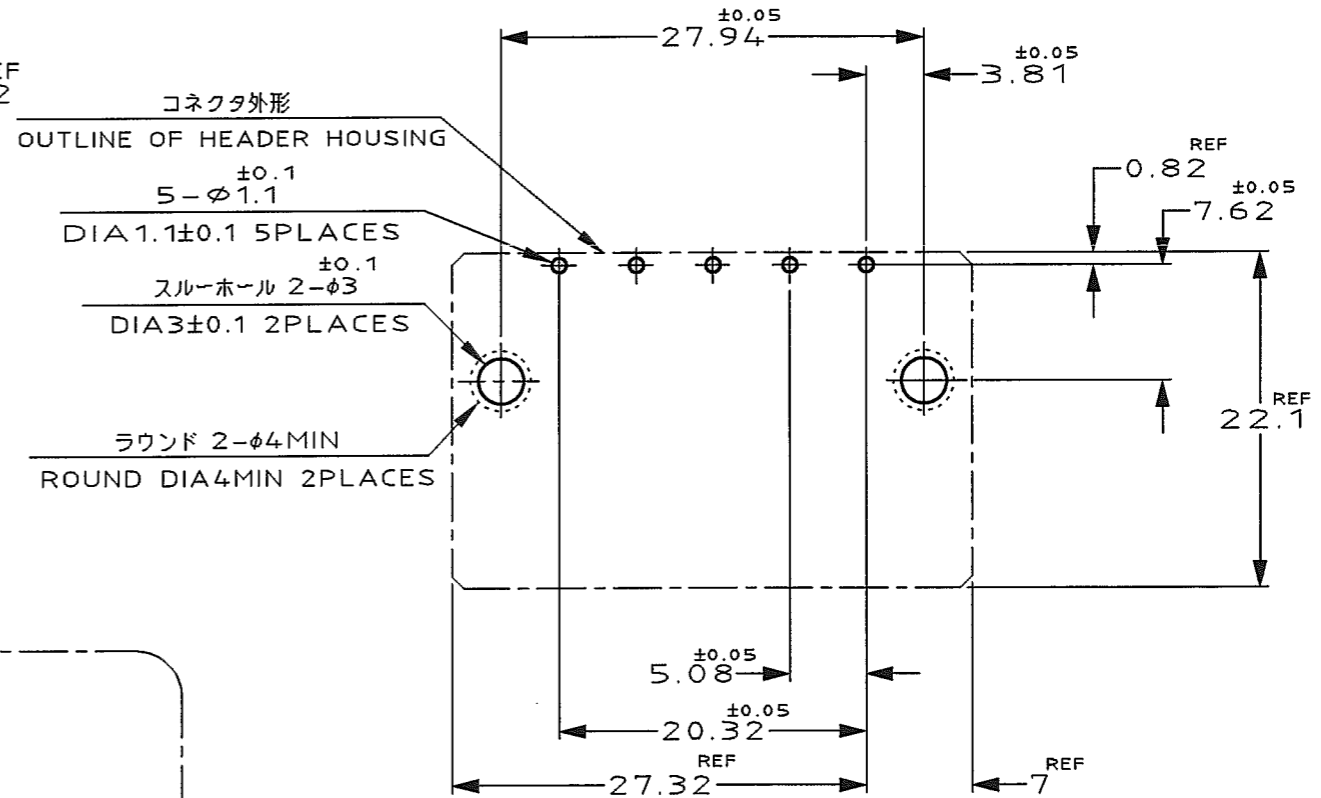
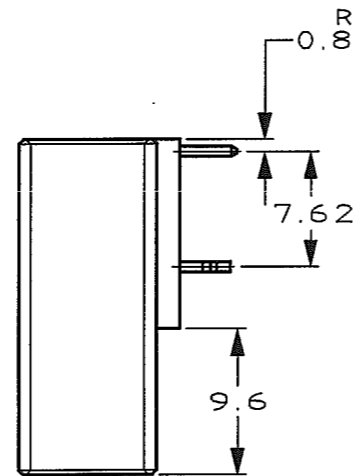
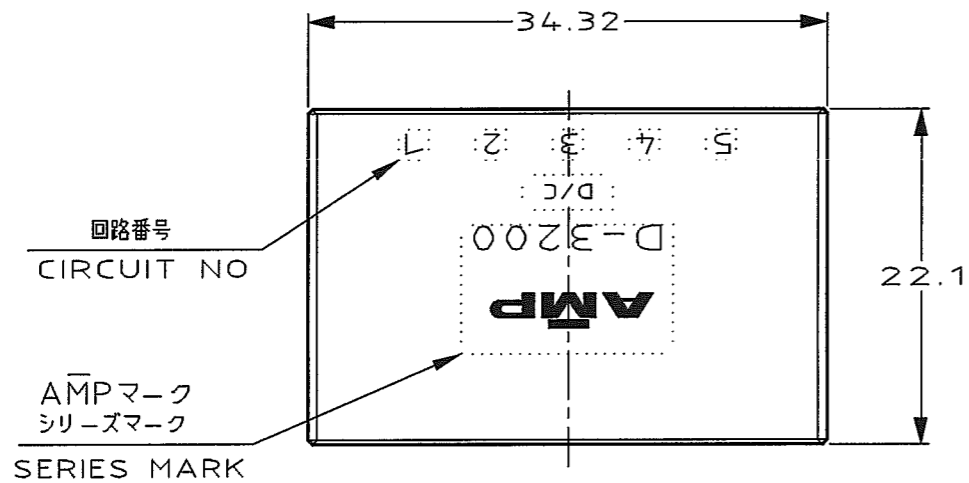
NUMBER 316130

3rd ANGLE PROJECTION

METRIC

DIMENSIONS IN MILLIMETERS. DO NOT SCALE PRINT

PRINT DIST



推奨基板取付け穴寸法
PC 基板厚: 1.6±0.1
(非累積公差)
(コネクタ搭載面)

RECOMEND PC BOARD HOLE PATTERN
PC BOARD THICKNESS: 1.6±0.1
(NOT ACCUMULATE TOLERANCE)
(CONNECTOR MOUNT SIDE)

NOTES

- MATERIAL: HOUSING: GLASS FILLED THERMO PLASTIC, POLYESTER
CONTACT: COPPER ALLOY
RETENTION LEG: COPPER ALLOY
- FINISH (CONTACT AREA): 0.38 μm MIN GOLD PLATING OVER Ni PLATING
- FINISH (CONTACT AREA): 0.76 μm MIN GOLD PLATING OVER Ni PLATING
- FINISH (CONTACT AREA): 2.0 μm MIN TIN PLATED OVER NICKEL
- FINISH (RETENTION LEG): TIN LEAD PLATED (CONTACT TAIL) OVER NICKEL
- FINISH (RETENTION LEG): TIN PLATED (CONTACT TAIL) OVER NICKEL
- OBSOLETE PARTS: OBSOLETE CIS STREAMLINING PER D.RENAUD/D.SINISI

注記

- 材料: ハウジング: ガラス入り熱可塑性ポリエステル樹脂
コンタクト: 銅合金
リテンションレグ: 銅合金
- めっき: コンタクト: 全面Ni下地
接触部: 0.38 μm MIN金めっき
- めっき: コンタクト: 全面Ni下地
接触部: 0.76 μm MIN金めっき
- めっき: コンタクト: 全面Ni下地
接触部: 2.0 μm MINスズめっき
- めっき: リテンションレグとコンタクト半田付部
: ニッケル下地の上に半田めっき
- めっき: リテンションレグとコンタクト半田付部
: ニッケル下地の上にスズめっき

△6	△4	2-316130-5	Y	OBSOLETE
△6	△3	2-316130-3	Y	
△6	△2	2-316130-2	Y	
△6	△4	1-316130-5	X	
△6	△3	1-316130-3	X	
△6	△2	1-316130-2	X	
(FINISH)		製品番号 (PART NO.)	KEY	

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WIRE RANGE			INSULATION DIA		NAME	
mm(AWG)			mmφ		5 POS SINGLE ROW HORIZONTAL HDR ASS'Y FOR DYNAMIC D-3200	
B1	ECO-10-000445	KK AEG JAN10			一般公差 (GENERAL TOLERANCE)	
B	REVISED(FJD0-0039-03)	TS SA 03	MATERIAL SEE NOTE 注記参照		100% ±0.2	
A	REVISED(FJD0-0114-03)	TS SM 03	FINISH SEE NOTE 注記参照		100% 300% ±0.3	
0	RELEASED (FJ00-2557-95)	KI YI 93	DR. 26/JUL/95 K.IKEDA		300% 100% ±0.4	
LTR	REVISION RECORD	DR CHK DATE	CHK. 31 JUL 95 Y.ISHIKAWA		APP. 31 JUL 95 S.MANABE	
					SIZE	LOC
					A3	J
					SCALE	REV.
					2-1	B1
					NUMBER	SHEET
					C= 316130	1 OF 1

单击下面可查看定价，库存，交付和生命周期等信息

[>>TE Connectivity\(泰科\)](#)